

13 **S1. Synthesis**.

14 **Thiophenol (HS(Ph)1).** We synthesized thiophenol according to a procedure reported in the 15 literature.¹ Bromobenzene (2.00 mL, 20.00 mmol), ethane-1, 2-dithiol (2.01 mL 24.00 mmol), 16 KOH (5.60 g, 100.00 mmol) and CuSO₄·5H₂O (0.16 g, 5 mol%), were heated at 120 °C in DMF 17 (50.00 mL) under N₂ for 24 hours. The mixture was extracted three times with CH₂Cl₂ (3×100) 18 mL), washed with brine $(3 \times 100 \text{ mL})$ after cooling down to room temperature. The combined 19 organic phases were then dried over Na2SO4, filtered and concentrated under reduced pressure. 20 The product thiophenol (0.24 g, yield 11.0%) was then purified by column chromatography 21 (silica gel, CH₂Cl₂/petroleum ether = $1/2$ v/v). 1H NMR (400 MHz, DMSO-d6) δ 7.56 – 7.49 22 (m, 2H), 7.39 (t, J = 7.7 Hz, 2H), 7.34 – 7.25 (m, 1H). HRMS (ESI⁺): m/z calc for C₆H₇S 23 [M+H]⁺ 111.0268, found 111.0257.

26 **Fig. S1.** ¹H NMR spectrum for $HS(Ph)$ ₁ in DMSO.

28 **Fig. S2.** The HRMS spectrum of $HS(Ph)₁$.

30 **4-Terphenylthiol (HS(Ph)3).** We synthesized 4-Terphenylthiol by the same procedure of 31 HS(Ph)₁.¹ 4-bromo-p-terphenyl (3.09, 10.00 mmol), ethane-1,2-dithiol (1.00 mL 12.00 mmol), 32 KOH (2.80 g, 50.00 mmol) and CuSO₄·5H₂O (0.08 g, 5 mol%), were heated at 120 °C in DMF 33 (30.00 mL) under N₂ for 24 hours. The mixture was extracted three times with CH₂Cl₂ (3 \times 100 34 mL), washed with brine $(3 \times 100 \text{ mL})$ after cooling down to room temperature. The combined 35 organic phases were then dried over $Na₂SO₄$, filtered and concentrated under reduced pressure. 36 The product thiophenol (0.24 g, yield 9.0%) was then purified by column chromatography 37 (silica gel, CH₂Cl₂/petroleum ether = $1/2$ v/v). ¹H NMR (400 MHz, Chloroform-*d*) δ 7.70 – 7.61 38 (m, 6H), 7.58 (d, *J* = 8.5 Hz, 2H), 7.46 (t, *J* = 7.6 Hz, 2H), 7.35 (d, *J* = 8.5 Hz, 3H). HRMS 39 (ESI⁺): m/z calc for C₁₈H₁₅S [M+H]⁺ 263.089, found 263.089.

41 **Fig. S3.** ¹H NMR spectrum for $HS(Ph)$ ₃ in CDCl₃.

S2. Sample preparations.

 Template-stripped Au surfaces (AuTS). AuTS substrates were prepared following procedures reported previously.² Briefly, we deposited a 200 nm thick Au (Au with a purity of 99.999% 49 from Dimu Materials, Inc (China)) film on clean Si (100) wafers with a native $SiO₂$ surface layer by thermal deposition (KYKY-400, Zhongke Ke Yi, China) with the base pressure being 2×10^{-5} Pa and the evaporation rate was about 0.2 Å s⁻¹ for Au at the first 50 nm and then

52 increased to \sim 1 Å s⁻¹ for the rest 150 nm. The glass slides (1.5 \times 1.5 cm²) were ultrasonically 53 cleaned with acetone and then ethanol for 20 minutes, and the slides were blown to dryness in 54 a stream of N_2 gas. After we cleaned the glass slides by a plasma of air for 5 mins at a pressure 55 of 100 Pa, the glass slides were glued on the Au surfaces by photo-curable optical adhesive 56 (Norland, No. 61). A 100 Watt UV lamp was used to cure the optical adhesive for 1 hour at a 57 distance of 60 cm from the light source. The Au surface that had been in contact with the $Si/SiO₂$ 58 wafer was lift-off by a razor blade.

59 **Direct deposition of Au (AuDE).** As described before,³ the thermal evaporator was applied to 60 deposit Au on the Si wafers under high vacuum $(2 \times 10^{-5}$ mbar) and the deposition rate and film 61 thickness were two significant parameters to determine the surface roughness, and the receipt 62 we used for i) Au^{DE1} (rms = 1.3 nm, a 5 nm layer of Cr at rate of 0.1 Å s⁻¹ followed by 200 nm 63 of Au at a rate of 1 Å s⁻¹), ii) Au^{DE2} (rms = 2.2 nm, a 20 nm layer of Cr at rate of 1 Å s⁻¹ followed 64 by 200 nm of Au at a rate of 5 Å s⁻¹) and iii) Au^{DE3} (rms = 3.2 nm, a 40 nm layer of Cr at rate 65 of 1 Å s⁻¹ followed by 400 nm of Au at a rate of 5 Å s⁻¹). To eliminate surface contamination 66 from the ambient, the Au^{DE} surfaces removing from the vacuum chamber were immediately 67 used to form SAMs.

SAMs preparation. All thiol terminated molecules except $HS(Ph)$ ₁ and $HS(Ph)$ ₃ were purchased from Sigma Aldrich with their highest purity (at least >98%) that we can found. To 70 form SAMs, Au substrates were immersed in degassed 3 mM ethanolic solutions of HSC_m (m 71 = 4, 6, 8) and $\text{HS}(Ph)_{n}$ (n = 1, 2, 3) over a period of time of 3 h under an inert nitrogen environment. The SAMs were rinsed with ethanol (AR grade) to remove the physisorbed molecules, dried in a stream of dry nitrogen gently and used for experiments within minutes to avoid degradation of the S-Au bond and surface contaminations.

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S3. Sample Characterizations.

 Atomic Force Microscope (AFM). The AFM images were recorded by Bruker Dimension FastScan AFM with tapping mode tips (Dimension, resonant frequency: 1.4 MHz, force 80 constant: 18 N m⁻¹). We measured three 1×1 µm and three 5×5 µm images on three substrates for each type of surfaces. The AFM software NanoScope Analysis (version 1.8) was used to analyze the AFM images for topography and the rms roughness.

 X-ray Photoelectron Spectroscopy (XPS) Measurements. XPS was used to characterize the 84 SAMs of HSC_m and $HS(Ph)_n$ with instruments located in National Center of Electron Spectroscopy in Beijing. The energy of the incident X-ray beam (1486.6 eV) was used with the Thermo Scientific K-Alpha XPS system. We recorded the high-resolution XPS spectra of S 2*p*, C 1*s* and Au 4*f*. In analysis, we used the least-square peak fit with a pseudo-Voigt function (a 88 linear combination of Lorentzian (30%) and Gaussian (70%) functions)⁴ to fit the XPS spectra with Avantage software, and the sloping background was modelled using a smart background correction.

 The physical absorbed molecules with binding energy being about 161eV of S *2p* 92 spectrum⁵ can be observed for HS(Ph)_n (n = 1, 2, 3) anchored on Au^{DE} electrode with rms 93 roughness being 3.2nm (Fig. S24). In contrast, HSC_m, based on S 2p spectrum (Fig. S26), were relatively densely assembled without physical absorbed molecules on rough Au substrate, indicating that the topography of bottom-electrode had more remarkable impacts on packing of 96 conjugated molecules, the explanations of which was that $HS(Ph)$ _n SAMs anchored on rough 97 bottom-electrode with extremely deteriorated packing and destroyed $\pi - \pi$ interactions of 98 $HS(Ph)_n$ for their more rigid nature.

 Ultraviolet Photoelectron Spectroscopy (UPS) Measurements. Work functions (WF) and HOMO energy were detected by UPS function installed in the Thermo Scientific K-Alpha XPS system. A specially designed biasing stage, which is in electrical contact with the analyzer, was

 applied to hold the samples. All measurements were performed in an ultrahigh vacuum chamber 103 with a base pressure of 1×10^{-8} pa. To probe the valence band, the photon energy at 21.22 eV was used and –10 V bias was applied to the sample to overcome the work function of the analyzer. All UPS spectra were referenced to the Fermi edge of Au.

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107 **S4. Electrical and thermoelectrical measurements**.

108 **Electrical Measurements and Analysis.** We followed previously reported procedures ² to 109 form the SAM-based junctions with cone-shaped tips of $Ga_2O_3/EGaIn$. The Au substrate was 110 grounded and the top-electrode was biased from $0V \rightarrow 0.5 V \rightarrow 0V \rightarrow -0.5 V \rightarrow 0V$, with a 111 step size of 50 mV, and a delay of 0.1 s, in all of our experiments. We measured three substrates 112 to obtain \geq 20 junctions, for each of which we collected 20-24 *J(V)* traces (that is a total of \sim 480 113 *J*(*V*) traces for each type of SAM). The *J*(*V*) data was analyzed following previously reported 114 procedures. ⁶ Briefly, we plotted the histogram of log|*J*| for each bias and fitted Gaussians to 115 the histograms to obtain the log-mean (μ_{log}) of the values of *J* and their log standard-deviations 116 (σ_{log}) .

117 **Analysis of relationship between measured** ∆ **and** *S***.** A polyimide (PI) film embedded with 118 heating resistors is used to heating the Au electrode to generate temperature difference 119 ($\Delta T = 0$ ~8 K) across the junctions (Fig. 1a, b). Firstly, control experiments were performed on 120 clean Au surfaces with different surface roughness that were absent of molecules (Fig. S7, S9). 121 We supposed that the temperature difference was mainly distributed across EGaIn and tungsten 122 tip (W tip) because the thermal conductivity of EGaIn ($G_{th, EG}$ ~26.43 W m⁻¹ K⁻¹)⁷ is far 123 overweight that of the surrounding air $(-0.024 \text{ W m}^{-1} \text{ K}^{-1})$. Wherein at Fig. S5, the difference 124 between *V*₁ and *V*₃ represents the measured ΔV , T_1 and T_3 denote room temperature. *V*₂ and T_2 125 are the potential and temperature measured by thermocouple of Au surface, respectively. 126 Therefore, the relationship between measured ∆V and *S* for Au/EGaIn junctions can be generally 127 depicted as Equation. (S1-S4)

128
$$
S_{EGaln} = -\frac{V_1 - V_2}{T_1 - T_2}
$$
 (S1)

129
$$
S_W = -\frac{V_3 - V_2}{T_1 - T_2}
$$
 (S2)

130
$$
V_1 - V_3 > 0
$$
, $T_1 - T_2 < 0$, $S_{EGaln} - S_W > 0$ (S3)

131
$$
S_{EGaln} - S_W = -\frac{V_1 - V_2 - V_2 + V_2}{T_1 - T_2} = -\frac{V_1 - V_3}{T_1 - T_2}
$$
(S4)

132 Fig. S21-S22 shows plot of Δ*V* as a function of Δ*T* for Au/EGaIn junctions with different 133 surface roughness. It can be found that the measured thermoelectric voltage is nearly 134 independent with the surface roughness of bottom electrode, according to $S = -\frac{\Delta V}{\Delta T}$, and the ΔT 135 obtained *S* is ~2.0 μV K⁻¹. Considering the thermopower of W tip (*S_W*) is 1.0 μV K⁻¹,⁸ and 136 hence, the thermopower of EGaIn (S_{EGaln}) is 3.0 µV K⁻¹.

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141 In the case of SAMs anchoring on Au electrode (Fig. S6), we defined *T*1, *V*¹ and *T*4, *V*⁴ were the 142 temperature (room temperature) and potential of Syringe and W tip away from SAMs, 143 respectively. T_2 and V_2 were the temperature measured by thermocouple potential of Syringe 144 close to SAMs. *V*³ and *T*³ are the potential and temperature of Au surface. Theoretically, the 145 temperature gradient was supposed to locate across SAMs because the thermal conductivity of 146 n-alkanethiolates $({\sim}18$ pW/K $){}^9$ was 3 orders of magnitude smaller than that of EGaIn $147 \frac{(\Delta T_1 = (T_1 - T_2) \cdot \Delta T_2 = (T_2 - T_3))}{(T_2 - T_3)}$, however, the measured T_2 was higher than room temperature

148 and approximately half as T_3 probably due to heat radiation ($\Delta T = \Delta T_1 \approx \Delta T_2 = \frac{1}{2} \Delta T_3 - (T_1 - T_3)^2$). 1 $\frac{1}{2}\Delta T_3 = (T_1 - T_3)$ 149 Hence, the relationship between measured ΔV and *S* for Au/SAM//Ga₂O₃/EGaIn junctions can 150 be generally depicted as Equation. (S5-S9)

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$$
S_{EGaln} = -\frac{V_1 - V_2}{T_1 - T_2} = -\frac{\Delta V_1}{\Delta T_1}
$$
 (S5)

152
$$
S_{SAM} = -\frac{V_2 - V_3}{T_2 - T_3} = -\frac{\Delta V_2}{\Delta T_2}
$$
 (S6)

153
$$
S_W = -\frac{V_4 - V_3}{T_4 - T_3} = -\frac{\Delta V_3}{\Delta T_3}
$$
 (S7)

$$
S_{EGaln} + S_{SAM} - 2S_W = -\frac{V_1 - V_4}{\Delta T}
$$
(S8)

155
$$
S_{SAM} = -\frac{V_1 - V_4}{\Delta T} - S_{EGaln} + 2S_W = -\frac{V_1 - V_4}{\Delta T} - 1
$$
 (S9)

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159 **Thermopower of commercial silicon wafer.** To verify that our platform can measure 160 thermopower precisely, we measured the Seebeck effects of commercial silicon wafer by EGaIn top-contacts, including P-type and N-type and the results are shown in Fig. S7-S8. It is evidence that the thermoelectric voltage is positively-changed for P-type Si supporting holes transport once heating bottom electrode, and negatively-changed for N-type Si owing to charge transport 164 being dominated by electrons. The measured values of *S* for N-type and P-type Si are 309.3 \pm 165 7.8 µV K⁻¹ and -286.3 ± 26.3 µV K⁻¹, respectively, similar to the reported values.¹⁰ The sign of *S* were determined by the nature of charge carriers with either electrons or holes. Fig. S8f shows schematic diagram of thermoelectric test of Si, where a copper wire was attached to the bottom surface of silicon wafer, ensuring that the carriers mainly migrate along the longitudinal direction during test.

172 **Fig. S7.** Thermoelectric potential of $\frac{Si}{Ga_2O_3/EG}$.

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175 **Fig. S8.** Thermoelectric potential of Cu//Si//Ga₂O₃/EGaIn junction at different *ΔT* for P-type Si (a) and N-type Si 176 (c), (b, d) corresponding histograms of ΔV with a Gaussian fit to these histograms, (e) plot of ΔV as a function of 177 *ΔT* for of N-type and P-type Si, (f) Schematic diagram of thermoelectric test of Si, where a copper wire was 178 attached to the bottom surface of the wafer. 179

 The measurement accuracy and error analyses for Seebeck coefficient. The accuracy of our thermal voltage measurement includes two parts: i) the accuracy of the output voltage and ii) the accuracy of the input temperature. Firstly, Fig. S9 shows the accurate voltage measurement was obtained by the voltmeter (2182A Nanovoltmeter, Keithley Inc., USA) with a detection 184 limit of 0.001μ V. Considering the loss at the electrical circuit (mainly at the connection points), 185 so we take the significant digit of the thermovoltage in this work as 0.01μ V.

187 **Fig. S9.** The voltmeter (2182A NANOVOLTMETER, KEITHLEY Inc., America) we utilized to measure 188 the voltage with accurate measurement of 0.001μ V.

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190 Secondly, the input temperature was monitored by a thermal couple with a detection limit of 191 0.01K. Therefore, we estimate the accurate significant digit of temperature was 0.1K in this 192 study. Typical temperature-time trace is shown in Fig. S10. Wherein, *T¹* is the room 193 temperature, the average of T_I (< T_I >) and its standard deviation could be obtained over ~100 s 194 test duration with a Gaussian fit. Once we heated the bottom-electrode, ΔT occurred. When 195 reaching thermal equilibrium, the average of T_2 ($\leq T_2$) and its standard deviation could be 196 obtained over ~200 s test time with a Gaussian fit. Then ΔT was obtained by using <*T*₂> 197 subtracting $\langle T_1 \rangle$. We recorded at least 20 junctions to generate a histogram of ΔT that can be 198 fitted with Gaussians to determine the mean value of ΔT (< ΔT) and the corresponded standard-199 deviation, as shown in Fig. S10c. Hence, the error of ΔT is 0.1K, accounting for ~2.5%. Since 200 the error of *S* originated from ΔV and ΔT , that of the former ($\sigma_{\Delta V}$) can be obtained from the 201 results of linear fitting in Fig. 3 and the latter (σ_{AT}) can be calculated from Fig. S10.

203 **Fig.** S10. (a) Temperature-time trace, (b) the related plot of ΔT against number of junctions, (c) the 204 corresponded plot of histograms of < ΔT (the mean value of ΔT) over 20 junctions with a Gaussian fit.

205 **Determination of power factor (PF).** We determined PF of HSC_m (m = 1, 2, 3) and $HS(Ph)_n$ 206 ($n = 1, 2, 3$) according to a procedure reported in the literature.¹¹ The magnitude of electric field 207 intensity (*E*) can be given by:

208 $d \tag{S10}$ $E=\frac{V}{I}$ $\frac{v}{d}$ (GV m⁻¹) 209 where *V* is the applied voltage and *d* is the molecular length considering the tilt angle (30°) of

210 SAMs. The conductivity (σ) is the inverse of resistivity, and can be obtained as follows:

$$
\sigma = \frac{J}{E} (\mu S \, cm^{-1}) \tag{S11}
$$

212 *J* (A cm⁻²) is the current density. Using the calculated σ value and the measured *S*, the power 213 factor (PF) value was obtained according to the following relationship:

$$
PF = S^2 \sigma \left(\mu W \, K^{-2} \, m^{-1} \right) \tag{S12}
$$

215 It can be found that, based on UPS characterization (Table S1-S7), the location of HOMO 216 (E_{HOMO}) and energy offset (δE) were changed insignificantly for SAMs of HSC_m and HS(Ph)_n 217 with similar *l*, indicating the coincidence of corresponded electronic structure. Then, *S* and *G* 218 were lie on molecular length. $HS(Ph)$ ₁ with the smaller *l* (Table S8), possessed higher *G* than 219 that of HSC4, and theoretically larger PF. However, the physical absorbed molecules with 220 binding energy being \sim 161eV of S 2p spectrum can be observed for HS(Ph)₁ anchored on Au 221 electrode (Fig. S24). In contrast, $HSC₄$, based on S $2p$ spectrum (Fig. S26), were relatively 222 densely assembled without physical absorbed molecules on Au^{TS} substrate. And the more rigid 223 nature of $HS(Ph)$ ₁ could deteriorate SAMs packing, leading to the reduced number of molecules 224 participating electron tunneling and lower *S*. In this case, the value of PF was dominated by S 225 for HS(Ph)₁ and HSC₄. In contrast, the *l* of HS(Ph)₂ and HS(Ph)₃ were larger than that of HSC₆ 226 and HSC_8 , respectively. In this case, PF of SAMs assembled on Au^{TS} electrode was mainly 227 depended on *G*. Increased molecular length contributed to the enhanced electron tunneling 228 distance and decreased G and inferior PF. Therefore, we qualitatively explain, from the 229 perspective of electron tunneling and molecular packing, that the PF of HSC_m was larger than 230 that of similar molecular-length $HS(Ph)$ _n by combining XPS and UPS result.

233 **Fig. S11.** The potential change of Au-S(Ph)₂//Ga₂O₃/EGaIn junctions for each spot with surface roughness 234 of Au electrode being 0.37 nm. of Au electrode being 0.37 nm.

235

237 **Fig. S12.** The potential change of Au-S(Ph)₂//Ga₂O₃/EGaIn junctions for each spot with surface roughness 238 of Au electrode being 1.30 nm. of Au electrode being 1.30 nm.

241 **Fig. S13.** The potential change of Au-S(Ph)₂//Ga₂O₃/EGaIn junctions for each spot with surface roughness 242 of Au electrode being 2.20 nm. of Au electrode being 2.20 nm.

243

245 **Fig. S14.** The potential change of Au-S(Ph)₂//Ga₂O₃/EGaIn junctions for each spot with surface roughness 246 of Au electrode being 3.20 nm. of Au electrode being 3.20 nm.

248 Fig. S15. The potential change of Au-S(Ph)₁//Ga₂O₃/EGaIn junctions for each spot with surface roughness of Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm. 251

253
254
255 Fig. S16. The potential change of Au-S(Ph)₃//Ga₂O₃/EGaIn junctions for each spot with surface roughness of Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm. 256

 $^{257}_{258}$ $\overline{258}$ **Fig.** S17. The potential change of Au-SC₄//Ga₂O₃/EGaIn junctions for each spot with surface roughness of 259 Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm. Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm.

 $\frac{261}{262}$ $\overline{262}$ **Fig. S18.** The potential change of Au-SC₆//Ga₂O₃/EGaIn junctions for each spot with surface roughness of 263 Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm. Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm. 264

 Fig. S19. The potential change of Au-SC₈//Ga₂O₃/EGaIn junctions for each spot with surface roughness of Au electrode being (a) 0.37 nm, (b) 1.30 nm, (c) 2.20 nm and (d) 3.20 nm.

270 272 histograms of Au-S(Ph)_n//Ga₂O₃/EGaIn and Au-C_n//Ga₂O₃/EGaIn with different surface roughness, including rms
273 = 0.37 nm, rms = 1.30 nm, rms = 2.20 nm and rms = 3.20 nm. $= 0.37$ nm, rms $= 1.30$ nm, rms $= 2.20$ nm and rms $= 3.20$ nm. 274

276 **Fig. S21.** The potential change of Au/EGaIn junction for each spot with different surface roughness, (a) rms $277 = 0.37$ nm, (b) rms $= 1.30$ nm, (c) rms $= 2.20$ nm and (d) rms $= 3.20$ nm. $= 0.37$ nm, (b) rms $= 1.30$ nm, (c) rms $= 2.20$ nm and (d) rms $= 3.20$ nm. 278

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280 **Fig. S22.** Plot of *ΔV* as a function of *ΔT* of Au/EGaIn junctions with different surface roughness. The solid lines are the linear fit.

284 **Fig. S23.** The histograms of $log_{10}lJ$ I at -0.5V with Gaussian fits for Au- S(Ph)₂//Ga₂O₃/EGaIn, where rms = 285 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm. 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm.

288 **Fig. S24.** The high resolution XPS S $2p$ spectra for Au-S(Ph)_n (n = 1, 2, 3) with different surface roughness, 289 including rms = 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm. including rms = 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm. 290 291

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293 **Fig. S25.** The high resolution XPS C 1*s* spectra for Au-S(Ph)_n (n = 1, 2, 3) with different surface roughness, 294 including rms = 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm. including rms = 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm.

296 **Fig. S26.** The high resolution XPS S $2p$ spectra for Au-SC_m (m = 4, 6, 8) with different surface roughness, 297 including rms = 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm. including rms $= 0.37$ nm, 1.30 nm, 2.20 nm, 3.20 nm.

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- 299 300
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- 302

305 **Fig. S27.** The high resolution XPS C 1s spectra for Au-SC_m (m = 4, 6, 8) with different surface roughness,

- including rms = 0.37 nm, 1.30 nm, 2.20 nm, 3.20 nm.
-

Fig. S28. Ultraviolet photoemission spectroscopy (UPS) for bare Au with diverse rms.

Sample	$E_{\text{cut off}}^{\text{(eV)}}$	WF (eV)
$rms=0.37$ nm	16.61	4.61
$rms=1.30$ nm	16.63	4.59
$rms=2.20$ nm	16.50	4.72
$rms=3.20$ nm	16.70	4.52

311 **Table S1.** Properties of bare Au obtained by UPS.

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314 **Fig. S29.** Valence band and secondary cutoff spectra of the HOMO peak for Au-S(Ph)₁ measured by UPS.

315

316 **Table S2.** Properties of Au-S(Ph)₁ SAMs obtained by UPS.

Sample	δE (eV)	$L_{\text{cut off}} (eV)$	WF (eV)	(eV) HOMO
$rms=0.37$ nm	2.17	16.64	4.58	-6.75
$rms=1.30$ nm	2.18	16.50	4.72	-6.90
$rms=2.20$ nm	2.20	16.47	4.75	-6.95
$rms=3.20$ nm	2.20	16.73	4.49	-6.69

319 **Fig. S30.** Valence band and secondary cutoff spectra of the HOMO peak for Au-S(Ph)² measured by UPS.

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321 **Table S3.** Properties of Au-S(Ph)₂ SAMs obtained by UPS.

Sample	δE (eV)	cut off $\left(\text{eV}\right)$	WF (eV)	L_{HOMO} (eV)
$rms=0.37$ nm	2.14	17.40	3.82	-5.96
$rms=1.30$ nm	2.13	17.48	3.74	-5.87
$rms=2.20$ nm	2.34	17.66	3.56	-5.90
$rms=3.20$ nm	2.16	17.31	3.91	-6.07

324 **Fig. S31.** Valence band and secondary cutoff spectra of the HOMO peak for Au-S(Ph)₃ measured by UPS. 325

Sample	δE (eV)	$E_{\text{cut off}}^{\text{(eV)}}$	WF (eV)	$L_{HOMO}(eV)$
$rms=0.37$ nm	2.15	16.72	4.50	-6.65
$rms=1.30$ nm	2.15	16.78	4.44	-6.59
$rms=2.20$ nm	2.19	16.82	4.40	-6.59
$rms=3.20$ nm	2.40	16.82	4.40	-6.80

326 Table S4. Properties of Au-S(Ph)₃ SAMs obtained by UPS.

328

329 **Fig. S32.** Valence band and secondary cutoff spectra of the HOMO peak for Au-SC⁴ measured by UPS.

Sample	δE (eV)	$E_{\text{cut off}}$ (eV)	WF (eV)	(eV) HOMO
$rms=0.37$ nm	2.11	16.60	4.62	-6.73
$rms=1.30$ nm	2.21	16.63	4.59	-6.80
$rms=2.20$ nm	2.22	16.58	4.64	-6.86
$rms=3.20$ nm	2.17	16.61	4.61	-6.78

330 **Table S5.** Properties of Au-SC₄ SAMs obtained by UPS.

333 Fig. S33. Valence band and secondary cutoff spectra of the HOMO peak for Au-SC₆ measured by UPS.

334 **Table S6.** Properties of Au-SC₆ SAMs obtained by UPS.

Sample	δE (eV)	$L_{\text{cut off}} (eV)$	WF (eV)	(eV) HOMO
$rms=0.37$ nm	2.09	16.98	4.24	-6.33
$rms=1.30$ nm	2.17	16.91	4.31	-6.48
$rms=2.20$ nm	2.15	16.87	4.35	-6.50
$rms=3.20$ nm	2.24	17.06	4.16	-6.40

336

Sample	δE (eV)	$E_{\text{cut off}}^{\text{(eV)}}$	WF (eV)	$HOMO$ (eV)
$rms=0.37$ nm	2.17	16.96	4.26	-6.43
$rms=1.30$ nm	2.19	16.84	4.38	-6.55
$rms=2.20$ nm	2.20	16.71	4.51	-6.71
$rms=3.20$ nm	2.15	16.88	4.34	-6.49

339 **Table S7.** Properties of Au-SC₈ SAMs obtained by UPS.

342 **Fig. S35.** Plots of log $|J|$ at -0.50 V versus number of carbon atoms or aromatic rings for junctions

343 incorporating SAMs of (a) HSC_m (m = 4, 6, 8) and (b) $HS(Ph)_n$ (n = 1, 2, 3). The solid lines are fits to the

344 Simmons Equation.

347 Fig. S36. The power factor as a function of surface roughness. *S*, $\ln \sigma$ (at 0.1V) and PF as a function of rms 348 roughness for $HS(Ph)_{n}$ (n = 1, 2, 3) and HSC_m (m = 4, 6, 8). The dashed lines are a visual guide.

Table S8 Summary of molecular length (*d*) determined by ChemDraw software.

		HS(Ph) ₁	HS(Ph) ₂	$HS(Ph)_{3}$	HSC ₄	HSC ₆	HSC_8
	l(A)	4.59	8.72	12.92	5.27	7.82	10.37
351							
352							

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